PCN Number:		20150302000				PCN Da	te:	3/03/2015		
Title:	Title: Qualification of TI Taiwan as an Alternate Assembly and Test Site for PCM1807/8 devices in the TSSOP package						307/8			
Custom	er Contact:	PCN N	lanager	Dept:	Quality Ser	rvice	:S			
Proposed 1 st Ship Date:		te:	06/03/2015	5/03/2015 Estimated Sample Availab			Provided upon Request			
Change	Type:									
Asset Asset Asset Asset Asset Asset Asset Asset Asset Baset Asset Baset Asset Baset 	embly Site		Assembly P	rocess			Ass	embly Ma	ateria	ls
Desi	ign		Electrical S	pecificat	ion		Med	chanical S	Specif	ication
	: Site		Packing/Sh	ipping/L	abeling		Tes	t Process		
Waf	er Bump Site		Wafer Bum	p Materi	al		Wat	er Bump	Proce	ess
Waf	er Fab Site		Wafer Fab I	Materials	S		Wat	Wafer Fab Process		
			Part numbe	er chang	e					
			P	PCN De	etails					
Descrip	tion of Chang	e:		Description of Change:						
Texas Instruments is pleased to announce the qualification of TI Taiwan as an alternate Assembly and test site for the family of PCN1807/8 devices in the TSSOP package. There will be no construction differences between devices built between the 2 locations. Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.										
and test construc Test cove test MQ.	site for the far tion difference erage, insertio	mily of s betw	F PCN1807/8 d veen devices b	levices in ouilt betw	n the TSSOP ween the 2 l	pac ocat	ckage ions.	e. There	will b	e no
and test construc Test cove test MQ.	site for the far tion difference	mily of s betw	F PCN1807/8 d veen devices b	levices in ouilt betw	n the TSSOP ween the 2 l	pac ocat	ckage ions.	e. There	will b	e no
and test constructors Test coverest MQ. Reason	site for the far tion difference erage, insertio	mily of s betw	F PCN1807/8 d veen devices b	levices in ouilt betw	n the TSSOP ween the 2 l	pac ocat	ckage ions.	e. There	will b	e no
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and test constructors Test coverest MQ. Reason Continuit	site for the far tion difference erage, insertion for Change: ty of Supply	mily of s betw ns, co	F PCN1807/8 d veen devices b nditions will re	levices in uuilt betv emain co	n the TSSOF ween the 2 loonsistent wit	P pac ocat th cu	ckage ions.	e. There	will b	e no erified with

Changes to product identification resulting from this PCN:

Assembly Site		
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI

Sample product shipping label (not actual product label)





(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483\$I2 (P) (2P) REV: (V) 0033317 (20L) C\$0: SHE (21L) CCO:USA (22L) A\$0: MLA 23L) ACO: MY\$

Topside Device marking:

Assembly site code for MLA= K
Assembly site code for TAI= T

Product Affected						
	PCM1807PW	PCM1807PWR	PCM1808PW	PCM1808PWR		
	PCM1807PWG4	PCM1807PWRG4	PCM1808PWG4	PCM1808PWRG4		



Qualification Report

Green Mold Compound (4206193)and Pb-free Reflow for the TSSOP Package Family Approved 12/08/2004

Product Attributes

Attributes	Qual Device: BQ8015DBT	Qual Device: SN761676DA	Qual Device: TAS3103DBT	Qual Device: TPS54900PW	Supporting QBS: MSP430F2274IDA
Assembly Site	TAI	TAI	TAI	TAI	TAI
Package Family	TSSOP	TSSOP	TSSOP	TSSOP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Site	TSMC2	HIJI	DMOS5	DFAB	TSMC-WF3
Wafer Fab Process	0.5u TLP/TLM	-	1833C05	LBC4	0.35-DPTM-FLASH

- QBS: Qual By Similarity
- Qual Device BQ8015DBT is qualified at LEVEL2-260C
- Qual Device SN761676DA is qualified at LEVEL2-260C
- Qual Device TAS3103DBT is qualified at LEVEL2-260C
- Qual Device TPS54900PW is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: BQ8015DBT	Qual Device: SN761676DA	Qual Device: TAS3103DBT	Qual Device: TPS54900PW	Supporting QBS: MSP430F2274IDA
HAST	HAST 130C/85%RH	96 Hours	3/120/0	-	-	3/120/0	-
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
тс	Temperature Cycle - 65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High-Temp Storage, 170C	420 Hours	3/231/0	3/231/0	3/231/0	3/231/0	3/200/0
TS	Thermal Shock - 65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	-
HTOL	Life Test, 155C	240 Hours	3/120/0	-	-	3/120/0	-
FLAM	Flammability (IEC 695-2-2)		3/15/0	-	3/15/0	3/15/0	-
FLAM	Flammability (UL 94 V-0)		3/15/0	-	3/15/0	3/15/0	-

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

⁻ The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

⁻ The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

⁻ The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: a0195592007817132224

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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